



Available Reverse engineering report list

Analysis-I Tech Inc.
鼎強科技股份有限公司
地址：新竹市民權路 266 號 9F-1

Tel: 035-5311556
Fax: 035-5311526
percy@analysis-i.com
Web: www.analysis-i.com

Item	Type	Process	Description	STATUS
1.	TI - TPS82671	CMOS 0.22um 1P4M	600mA, DC/DC step-down power supply intended for low-power applications - Die size: 0.87mm*1.24mm=1.08mm ²	Full chip analysis Ready
2.	TI - TPS62671	CMOS 0.22um 1P4M	high-frequency synchronous step-down dc-dc converter optimized for battery-powered portable applications. Die size: 0.87mm*1.24mm=1.08mm ²	Full chip analysis Ready
3.	Goodix- GT967,GT968, GT927,GT928, GT915	CMOS 0.11um 1P6M	Capacitive Touch panel controller , support On-cell, PG, GG, GF, OGS , cover & sensor , 4"~10.1" , 5~10 points true touch Die size: 1.2mm*2.97mm	AFE circuit analysis Ready
4.	Synaptics - S3202A S3200	CMOS 0.18um 1P5M	Capacitive Touch panel controller Highly Accurate, Responsive 10-Finger Touch. Die size: 2.74mm*2.86mm	AFE,ADC circuit analysis Ready
5.	Silergy – SY8120	CMOS 0.5um 1P2M	High Efficiency Fast Response, 2A, 16V Input Synchronous Step Down Regulator Die size: 0.9mm*1.70mm=1.53mm ²	Full chip analysis Ready
6.	Fairchild - FAN302	CMOS 0.5um 1P2M	PWM controller significantly simplifies isolated power supply design that requires CC regulation of the output. Die size: 1.611mm*1.286mm	Analog circuit analysis Ready
7.	STMicroelect ronics – VN1160	CMOS 1.5um 1P1M	Direction indicator driver for motorbike. Die size: 2.412mm*2.080mm	Full chip analysis Ready
8.	Ensphere Solutions XVR10100	CMOS 65nm 1P7M	Dual 10Gbit/s Optical Transceiver for Light Peak. Die size: 2.25mm*0.90mm=2.03mm ²	Analog circuit Imaging Annotation Ready
9.	MPS MP1470	CMOS 0.35um 1P3M	High-Efficiency, 2A, 16V, 500kHz ,Synchronous, Step-Down Converter Die size : 1.23mm*0.87mm=1.07mm ²	Full chip photography Ready
10.	Apple iphone5	In-cell 4" - 326ppi	AMOLED panel analysis report iphone size : 123mm*58mm	Panel analysis structure Report
11.	TI BQ24196	CMOS 0.25um 1P4M	I2C Controlled 2.5A Single Cell USB/Adapter Charger With Narrow VDC Power Path Management and USB OTG Die size : 2.63mm * 2.61mm = 6.86 mm ²	Full chip analysis Ready
12.	TI LM3646	CMOS 0.25um 1P5M	1.5A Synchronous Boost Converter with Dual High-Side Current Sources and I2CCompatible Interface Die size : 1.95mm * 1.55mm = 3.02 mm ²	Analog circuit analysis Ready
13.	Mstar MSG2133A	CMOS 0.13um 1P7M	Touch screen controller Die size :2.60mm * 2.20mm	Partial circuit analysis Photography Ready
14.	Broadcom BCM5976	CMOS 0.13um 1P6M	Touch screen controller by Broadcom use to Apple iphone 5 / iPad mini / Macbook Air. Die size : 3.86mm * 3.23mm	Partial circuit analysis Photography Ready
15.	TI BQ24195	CMOS 0.25um 1P4M	I2C Controlled / 4.5A Single Cell USB/Adapter Charger With at 2.1A Synchronous Boost Operation FEATURES Die size : 2.63mm * 2.61mm = 6.86 mm ²	Full chip analysis Ready
16.	BCD GP 360H1M	BCD 0.6um 1P1M	AC-DC power supply controller for battery charger and adapter applications, It can meet less than 10Mw standby power for "super" charger. Die size : 1.70mm * 1.67mm	Full chip analysis Ready
17.	Synaptics S3528A,S5050 A, S5100A	CMOS 0.18um 1P5M	The Synaptics S3528A is a touch screen controller found in the HTC HTC6525L, (Die mark : " 2013 T1327A ") Die size : 4.02mm*3.64mm	AFE circuit analysis Ready



Available Reverse engineering report list

2 / 3
2019/06/13

Analysis-I Tech Inc.
鼎強科技股份有限公司
地址：新竹市民權路 266 號 9F-1

Tel: 035-5311556
Fax: 035-5311526
percy@analysis-i.com
Web: www.analysis-i.com

Item	Type	Process	Description	STATUS
18.	TI - TPS61280	CMOS 0.25um 1P 3M+RDL	Low-, Wide- Voltage Battery Front-End DC/DC Converter Single-Cell Li-Ion, Ni-Rich, Si-Anode Applications Die size : 1.63mm*1.63mm	Analog circuit analysis Ready
19.	ADI – AD7794	CMOS 0.35um 1P3M	low power, low noise, complete analog front ends for high precision measurement applications. They contain a low noise, 24-/16-bit Σ - Δ ADC with six differential inputs. Die size : 2.29mm*2.33mm	Analog circuit analysis Ready
20.	SEMTECH NT28L52	CMOS 0.13um 1P6M	Law power TIA 10GBASE-SR Ethernet and Wireless infrastructure. Die size : 1.12mm*0.88mm	Partial circuit analysis Ready
21.	Realtek ALC5672	CMOS 0.11um 1P6M	Multi-Channel Audio Hub/CODEC with Gen.3 Voice DSP and SoundReal™ Post-Processing for Mobile Devices Die size : 2.842*4.181mm	Analog circuit analysis Ready
22.	Focaltech FT8606	CMOS 0.11um 1P6M	IDC integrates driver controller , support a-Si TFT LCD HD. Die size : 32.0mm*1.0mm	AFE circuit analysis Ready
23.	Synaptics TD4191	CMOS 0.11um 1P6M	Touch and display driver integration (TDDI) delivers best-in-class capacitive sensing performance and industry-leading display noise management. Die size : 31.87mm*1.29mm	AFE circuit analysis Ready
24.	Richtek RT8487	CMOS 0.25um 1P2M	High Efficiency BCM LED Driver Controller for High Power Factor Offline Applications. Die size : 0.70mm*0.68mm	Full chip analysis Ready
25.	Gennum GN1068	CMOS 0.18um 1P6M	GN1068 4-16Gbps Rate Selectable Transimpedance Amplifier. 10 Gigabit Ethernet / Serial Data Systems up to 14.5Gbps . Die size : 1.16mm*0.85mm	Full chip analysis Ready
26.	Focaltech FT8716	CMOS 90nm 1P6M	IDC integrates driver controller , support a-Si TFT LCD HD. Die size : 32.0mm*1.0mm	LCD driver & AFE circuit analysis and ESD imaging Ready
27.	STM STM32L476	CMOS 90nm 1P7M	Ultra-low-power with FPU ARM Cortex-M4 MCU 80 MHz with 1Mbyte Flash, LCD, USB OTG Die size : 4.38mm*3.73mm	Analog part circuit Ready
28.	SKYRELAY ET6602	CMOS 0.18um 1P5M	ETC 5.8G solution Die size : 1.63mm*1.29mm	Full chip analysis Ready
29.	TI BQ27545	CMOS 0.25um 1P4M	Single Cell, Pack Side, Impedance Track Fuel Gauge Die size: 2.56mm*1.9mm	Analog part photography Ready
30.	AmbiQ mirco AM1805	CMOS 0.35um 1P3M	Real-Time Clock with Power Management Family provides a groundbreaking combination of ultra-low power coupled with a highly sophisticated feature set.	Analog part analysis Ready
31.	Richtek RT7239	CMOS 0.25um 1P3M	synchronous step-down DC-DC converter with advanced constant-on time (ACOT™) mode control. Die size : 1.56mm*1.68mm	Analog part analysis Ready
32.	TI BQ27441	CMOS 0.18um 1P4M	Battery Fuel Gauge offer fuel gauging solution for single series cell Li-ion battery packs. Die size: 1.56mm*1.51mm	Partial chip analysis Ready
33.	SEMTECH GN1190	CMOS 65nm 1P7M	Law power consumption, 210Mw typical for 4 channels. Use with GN1090 quad TIA. Die size : 1.73mm*0.84mm	AFE net list extraction. Ready



Available Reverse engineering report list

3 / 3
2019/06/13

Analysis-I Tech Inc.
鼎強科技股份有限公司
地址：新竹市民權路 266 號 9F-1

Tel: 035-5311556
Fax: 035-5311526
percy@analysis-i.com
Web: www.analysis-i.com

Item	Type	Process	Description	STATUS
34.	MPS – MP6507	CMOS 0.5um 1P 2M	2.7V-to-15V, 700mA, Bipolar Stepper-Motor Driver with Integrated MOSFETs Die size : 1.4mm*1.51mm	Analog circuit analysis Ready
35.	Realtek – RTL8201F	CMOS 0.11um 1P7M	Single-Chip/Port 10/100M Ethernet PHYceiver with Auto MDIX Die size : 0.974mm*1.461mm	Analog circuit analysis Ready
36.	EPMI – EP9555E	CMOS 0.18um 1P5M	Low Power 3-Port HDMI/MHL Receiver with Scaler and CCIR 656 Output Die size : 2.84mm*2.68mm	Analog circuit analysis Ready
37.	TI – THS6212	BCD 0.8um 1P 3M	Differential line-driver amplifier with a current-feedback architecture. support transmissions of 14.5-dBm line power up to 30 MHz. Die size : 1.783mm ×1.956mm	Analog circuit analysis Ready
38.	TI- TPS65651	CMOS 0.18um 1P4M	TPS65651 Triple-Output AMOLED Display Power Supply , Single-Wire Digital Interface for Programming. Die size : 1.63mm ×1.63mm	Analog circuit analysis Ready
39.	TI- LP5907	CMOS 0.18um 1P4M	LP5907 250-mA Ultra-Low-Noise, Low-IQ LDO, RF and analog circuits, high PSRR, low quiescent current, and low line or load transient response figures. Die size : 0.58mm ×0.58mm	Full chip analysis Ready
40.	Weltrend WT6615F	CMOS 0.18um 1P5M	Die Size: 2714 um x 2401um (w/i scribe line) WT6615F that supported USB3.0 and QUALCOMMQuick ChargeTM 3.0 / 4.0 for USB ,Type-C Charging applications.Circuit Analysis Report	Analog circuit analysis Ready
41.	TI – TPS62088	CMOS 0.13um 1P4M	Tiny 6-pin 3-A Step-Down Converter in 1.2-mm x 0.8-mm WCSP. Die size : 1.15mm ×0.75mm	Full chip analysis Ready
42.	Onsemi NCP137	CMOS 0.25um 1P4M	700 mA, Very Low Dropout Bias Rail CMOS Voltage Regulator. Die size : 1.15mm ×0.75mm	Full chip analysis Ready
43.	Nova- NT36625	CMOS 80nm 1P7M	TDDI Reverse report : Nova NT36625 TP Die size : 32.01mm ×1.00mm	AFE circuit analysis Ready
44.	RFMD – RFMD2080	CMOS 0.13um 1P6M	45MHz To 2700MHz IQ MODULATOR WITH SYNTHESIZER / VCO AND BASEBAND INTERFACE. Die size : 2.97mm ×3.32mm	Full chip analysis Ready
45.	SGMICRO SGM40658	CMOS 0.22um 1P3M+RDL	High-Current Over-Voltage Protector (5.97V) Die size : 1.26mm ×1.79mm	Partial circuit analysis Ready